

# PARA LIGHT ELECTRONICS CO., LTD.

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# DATA SHEET

# PART NO.: L-C170LGCT

REV: <u>C / 4</u>

CUSTOMER'S APPROVAL : \_\_\_\_\_ DRAWING NO. : DS-72-04-0001 \_\_\_\_\_ DCC : DATE : 2021-11-24

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### Part No. : L-C170LGCT

#### PACKAGE OUTLINE DIMENSIONS SIDE VIEW BACK VIEW TOP VIEW MOLDING BODY (LENS) 1.05 1.25 P.C BOARD R0.10 0.45 POLARITY LED DICE +SOLDERING TERMINAL CATHODE 2.00 1.50 REF. 0.95 0.45 5.00° 0.80 0.28 ~ 0.30 0.35

Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is  $\pm$  0.1mm (.004") unless otherwise noted.

#### Features

- \* Top view, wide view angle, single color Chip LED.
- \* Package in 8mm tape on 7" diameter reels.
- \* Compatible with automatic Pick & Place equipment.
- \* Compatible with Infrared and Wave soldering reflow solder processes.
- \* EIA STD package.
- \* I.C. compatible.
- \* Pb free product.
- \* Meet RoHS Green Product.
- \* Moisture sensitivity level: 3



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### • Chip Materials

- \* Dice Material : InGaN
- \* Light Color : Super Green
- \* Lens Color : Water Clear

### • Absolute Maximum Ratings(Ta=25°C)

Symbol	Parameter	Rating	Unit
PD	Power Dissipation	100	mW
IPF	Peak Forward Current	100	mA
IFF	(1/10 Duty Cycle, 0.1ms Pulse Width)	100	
IF	Continuous Forward Current	25	mA
VR	Reverse Voltage	5	V
ESD	Electrostatic Discharge Threshold(HBM)Note A	1000	V
Topr	Operating Temperature Range	-40 ~ +85	°C
Tstg	Storage Temperature Range	-40 ~ +85	°C

Note A :

HBM : Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

### • Electro-Optical Characteristics(Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Luminous Intensity	IV	180	300	710	mcd	IF=20mA
Viewing Angle	2 0 1/2		130		deg	Note 2
Peak Emission			510			Maaron (@Daala
Wavelength	$\lambda p$		518	nm	Measurement @Peak	
Dominant Wavelength	$\lambda d$	520	525	530	nm	IF=20mA
Spectral Line	Λλ		15			
Half-Width			15		nm	
Forward Voltage	VF	2.8	3.1	3.4	V	IF =20mA
Reverse Current	IR			50	μA	VR = 5V



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#### • Bin Code List

Luminous Intensity(IV), Unit:mcd@20mA			Forward Voltage(VF), Unit:V@20mA		
Bin Code	Min	Max	Bin Code	Min	Max
S	180	280	K8	2.8	2.95
Т	280	450	K9	2.95	3.10
U	450	710	K10	3.10	3.25
			K11	3.25	3.40

Tolerance of each bin are  $\pm 15\%$ 

Tolerance of each bin are  $\pm 0.1$  Volt

Dominant Wavelength (Hue), Unit: nm@20mA				
Bin Code	Min	Max		
AP	520	525		
AQ	525	530		

Tolerance of each bin are  $\pm 1$ nm

Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2.  $\theta$  1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength  $\lambda$  d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 4. Caution in ESD :

Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

5. Major standard testing equipment by "Instrument System" Model : CAS140B Compact Array Spectrometer and "KEITHLEY" Source Meter Model : 2400.



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### • Typical Electro-Optical Characteristics Curves

(25°CAmbient Temperature Unless Otherwise Noted)

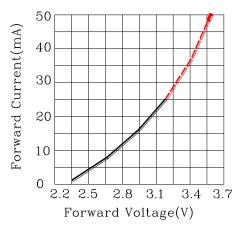


Fig.2 Forward Current vs.Forward Voltage

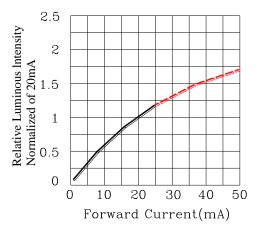


Fig.4 Relative Luminous Intensity vs.Forward Current

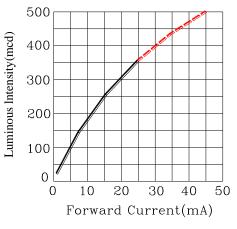


Fig.3 Luminous Intensity vs.Forward Current

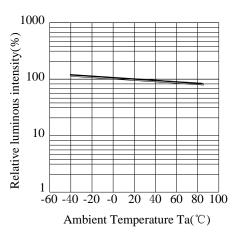
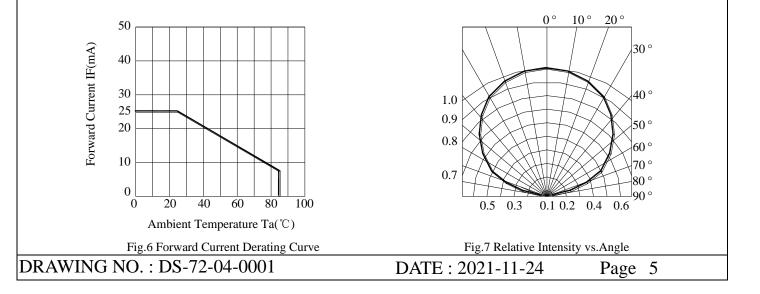


Fig.5 Luminous Intensity vs.Ambient Temperature





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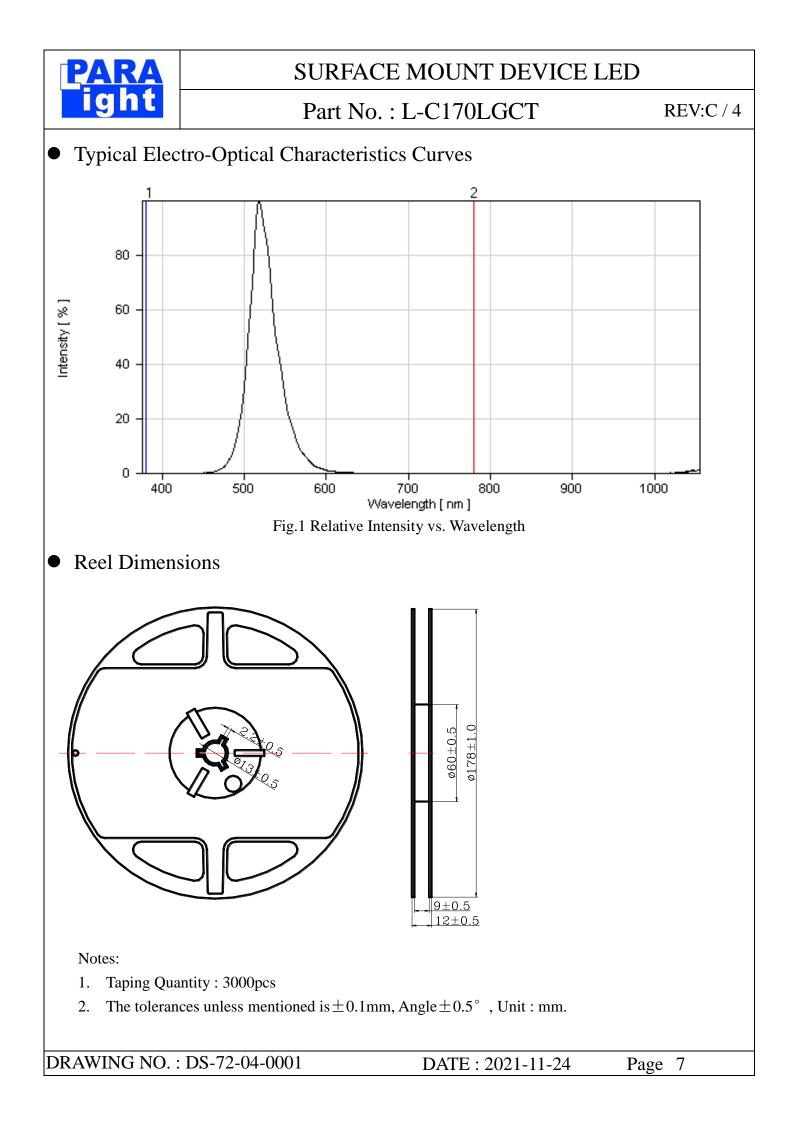
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#### • Label Explanation



#### ITEM CODE:PARA LIGHT PART NO: L-C170LGCT IV --- Luminous Intensity Code LOT NO: EM S L 12 09 0110 в F А C D Е A---EM: Emos Code B---S:SMD L---Local D---Year E---Month F---SPEC. PACKING QUANTITY OF BAG: 3000pcs for 150, 170, 110, 155, 115 series 4000pcs for 191 series 5000pcs for 192 series DATE CODE: <u>2012</u> <u>09</u> <u>10</u> G Η Ι G---- Year H--- Month I --- Day

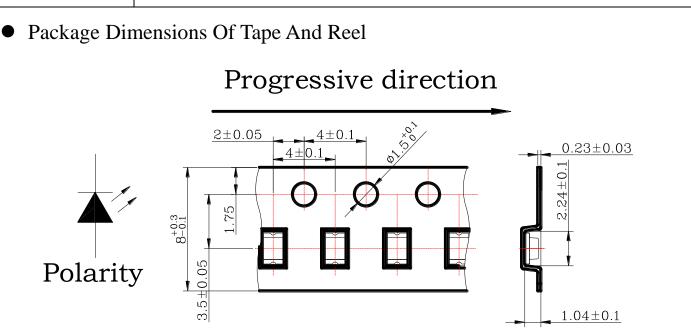
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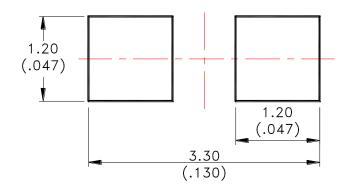
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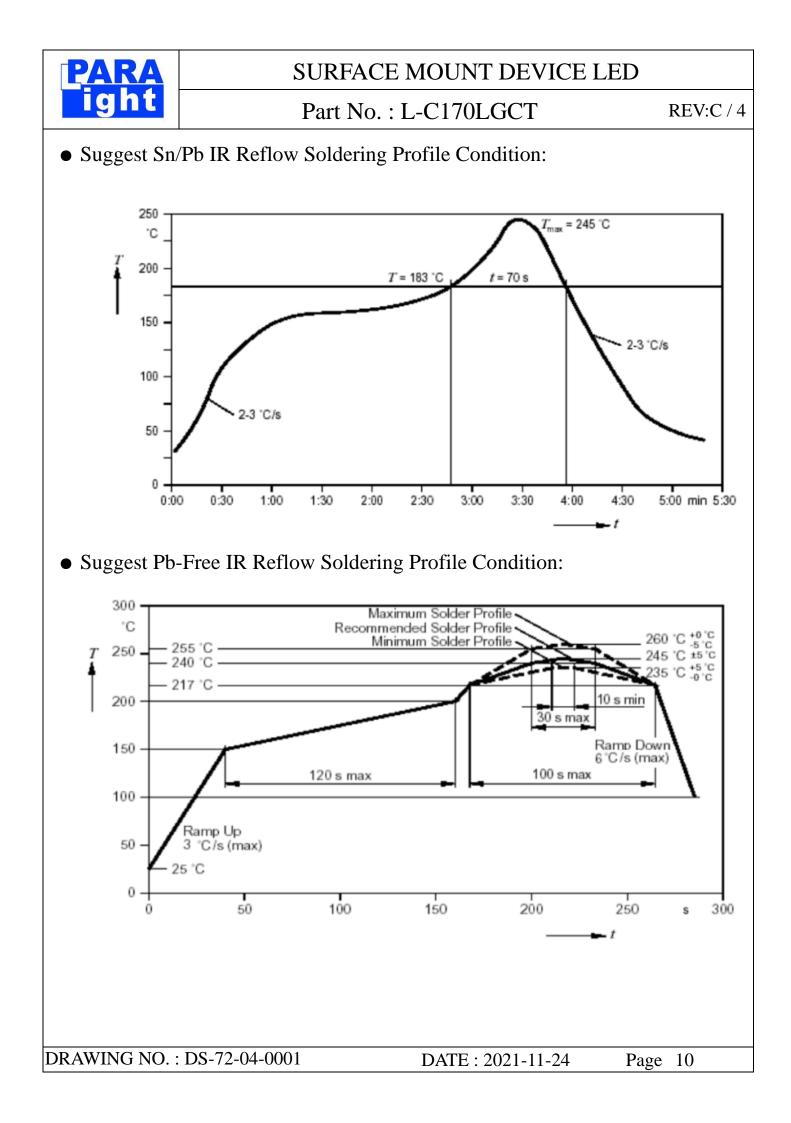
### • Cleaning

- \* If cleaning is required, use the following solutions for less than 1 minute and less than  $40^{\circ}$ C.
- \* Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- \* Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

### Suggest Soldering Pad Dimensions



Direction of PWB camber and go to reflow furnace





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### CAUTIONS

#### 1. Application Limitation :

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application).Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

#### 2.Storage :

Do not open moisture proof bag before the products are ready to use.

Before opening the package: The LEDs should be kept at  $30^{\circ}$ C or less and 90% RH or less.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours

#### 3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature. Recommended soldering condition.

Reflow Soldering :

Pre-heat 120~150 °C, 120sec. MAX., Peak temperature : 240 °C Max. Soldering time : 10 sec Max.

Soldering Iron : (Not recommended)

Temperature 300 °C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering.



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Wave soldering :

Pre-heat 100 °C Max, Pre-heat time 60 sec. Max, Solder wave 260 °C Max, Soldering time 5 sec. Max. preformed consecutively cooling process is required between 1<sup>st</sup> and 2<sup>nd</sup> soldering processes.

#### 4. Lead-Free Soldering

For Reflow Soldering :

- 1、Pre-Heat Temp:150-180°C,120sec.Max.
- 2. Soldering Temp:Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3、Peak Temperature:260°C, 5sec.
- 4. Reflow Repetition:2 Times Max.
- 5. Suggest Solder Paste Formula 93.3 Sn/3.1 Ag/3.1 Bi /0.5 Cu

For Soldering Iron (Not Recommended) :

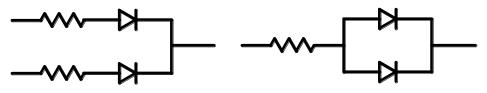
- 1. Iron Tip Temp:350°C Max.
- 2. Soldering Iron:30w Max.
- 3. Soldering Time: 3 Sec. Max. One Time.

For Dip Soldering :

- 1、 Pre-Heat Temp:150°C Max. 120 Sec. Max.
- 2、Bath Temp:265°C Max.
- 3, Dip Time:5 Sec. Max.
- 5. Drive Method

Circuit model A

Circuit model B



(A)Recommended circuit.

(B)The difference of brightness between LED's could be found due to the Vf-If characteristics of LED.